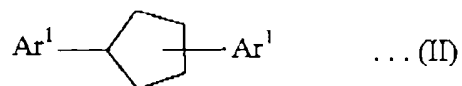
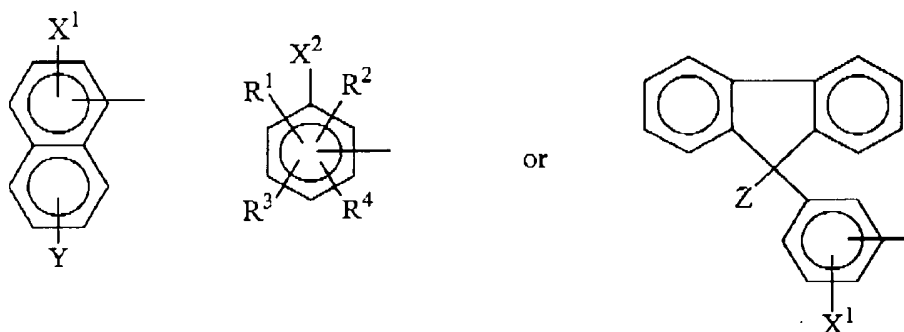


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wherein Ar^1 represents at least one of monovalent organic groups represented respectively by

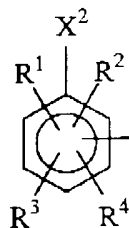


X^1 represents a hydroxyl group or a 2,3-epoxypropoxyl group; X^2 represents a 2,3-epoxypropoxyl group; Y represents a hydrogen atom, a hydroxyl group or a 2,3-epoxypropoxyl group; Z represents a hydrogen atom, a phenyl group, a hydroxyphenyl group or a 2,3-epoxypropoxyphenyl group; and R^1 to R^4 are each a group selected independently from a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom;

in a case where both Ar^1 's are

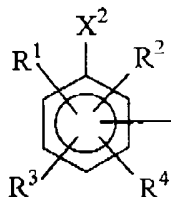
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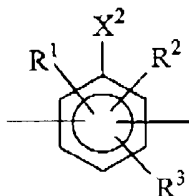


, the Ar¹'s are bonded respectively to 1 and 3 positions of the cyclopentane ring of formula (II).

16. (Amended) The compound according to claim 1, wherein the Ar¹ is a monovalent organic group represented by



and the Ar² is a divalent organic group represented by

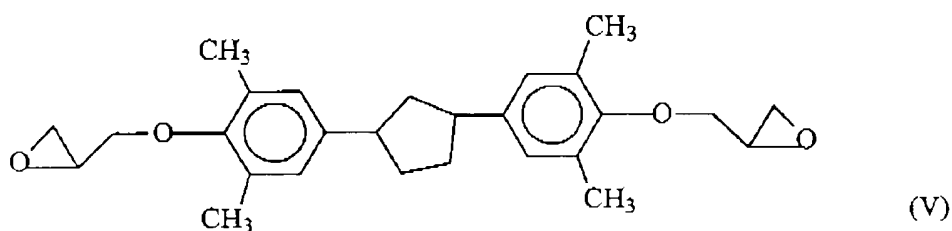


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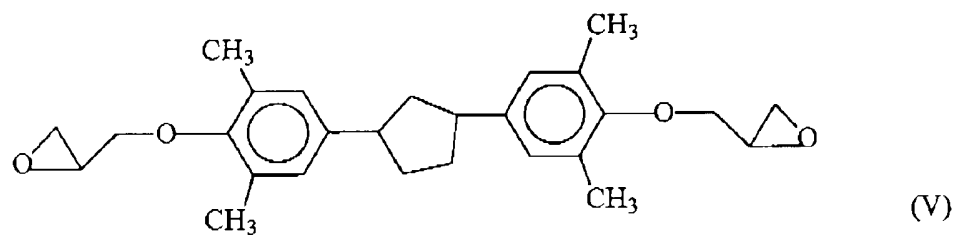
wherein X^2 represents a 2,3-epoxypropoxyl group; R^1 to R^4 are each a group selected independently from the group consisting of a hydrogen atom, an alkyl group and an aryl group having 1 to 10 carbon atoms and a halogen atom.

24. (Amended) A compound according to claim 23 having the formula (V)



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28. (Amended) An epoxy resin molding material according to claim 26 including a compound having the formula (VII)

